

**Amendments to the Specification:**

Page 14, please rewrite the paragraph commencing at line 9, as follows:

FIG. 12 shows an exploded view of the chassis 100 where the heat baffle components and cable guide components have been exploded. The details of the top horizontal surface 172 can be seen including the first ridge 176, second ridge 178, and recessed area 174 between the first and second ridges 176, 178. The first and second ridges 176, 178 are parallel to each other and are perpendicular to the longitudinal axis of the vertical sidewalls 102, 104. Also visible are card slots 194 for receiving a top edge of the modules 116 and divider slots 192 for receiving a top edge 171 of the divider walls 128, 130, 132, 170, and 134. As with the bottom horizontal surface 118, the ridges 176, 178 allow the card slots 194 to be included while maintaining the rigidity of the ~~to~~ top horizontal surface 172. Rather than being included in the ridges 176, 178, the card slots 194 extend across the recessed area 174 but not across the ridges 176, 178 to receive the top edge of modules 116.